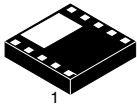


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

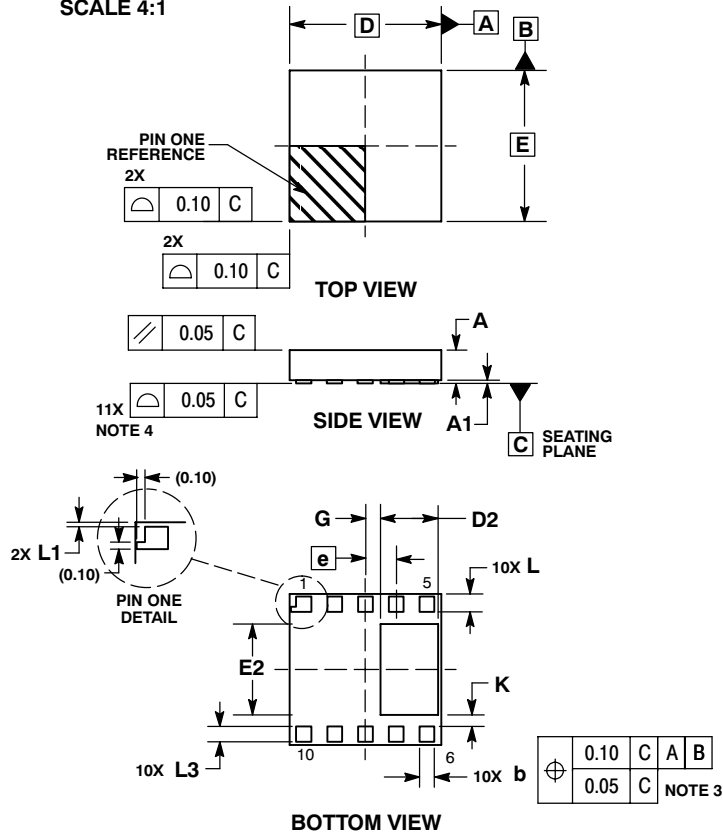
ON Semiconductor®



SCALE 4:1

LLGA10 2.5x2.5, 0.5P  
CASE 513AG-01  
ISSUE A

DATE 15 MAY 2007

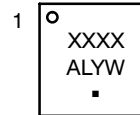


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.50	0.60
A1	0.00	0.05
b	0.20	0.30
D	2.50 BSC	
D2	0.90	1.00
E	2.50 BSC	
E2	1.45	1.55
e	0.50 BSC	
G	0.20	0.30
K	0.20	---
L	0.30 REF	
L1	0.05 BSC	
L3	0.20	0.30

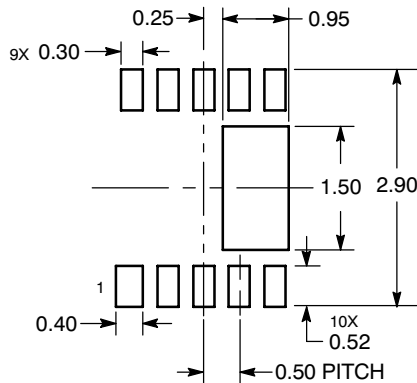
**GENERIC MARKING DIAGRAM\***



- XXXX = Specific Device Code
- AL = Assembly Location
- Y = Year
- W = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

**SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>10 PIN LLGA, 2.5X2.5, 0.5P</b>	<b>PAGE 1 OF 2</b>

